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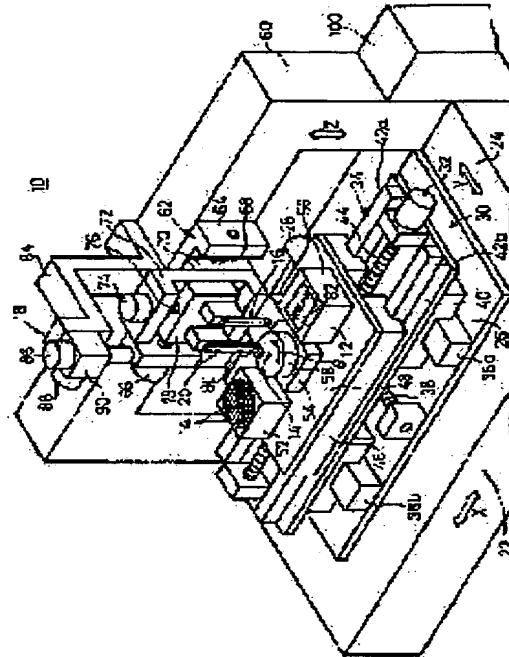
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(54) LIGHT EMITTING DEVICE BONDING METHOD AND EQUIPMENT

(57)Abstract:

PROBLEM TO BE SOLVED: To enable the emission center of a light emitting device to be very accurately positioned at a prescribed point on a board without being affected by variations in the external shape of the light emitting device.

SOLUTION: A light emitting device bonding equipment is equipped with a probe 16, which makes the LED chip 14 start emitting light before an LED chip 14 is bonded on a board 12, an imaging means 18, which recognizes the emission center of the LED chip 14 and does image recognition of the external shape reference point coordinates of the LED chip 14 with respect to the recognized emission center, and a light emitting device holding means 20 which positions the LED chip 14 at a bonding position on the board 12, resting on the basis of the external shape reference point coordinates subjected to image recognition.



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